



Carrier Solutions

Applications

- Glass carriers for temporary bonding in advanced semiconductor packaging processes such as Silicon wafer thinning and fan-out level processing

Benefits

- Tunable CTE and mechanical properties to meet various semiconductor process requirements
- Scalable form factor in both wafer and panel formats
- Low TTV and warp
- Optically transparent enabling UV or IR based debond processes and laser mark serialization
- Excellent chemical durability conducive to semiconductor process environments

Standard Options and Features

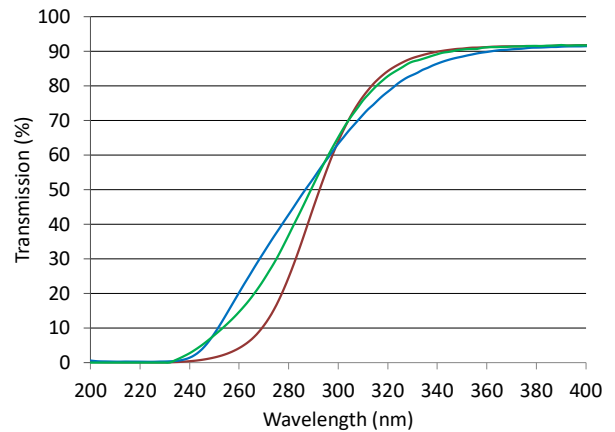
CTE Offerings	3.2 x10 ⁻⁶ /°C – 10x10 ⁻⁶ /°C
Form Factors	Wafers: 100mm – 450mm Panels: Up to 600mm x 600mm
Thickness	Wafers: 0.4mm – 1.1mm Panels: 0.7mm - 2.0mm
Edge Beveling	Radius (R) Type and Chamfer (C)
Surface Roughness	< 1.0nm
Features	Wafers: Semi-standard notch/flat Panels: Orientation corner profiles
Surface ID Marking	Semi-standard or custom

Properties*

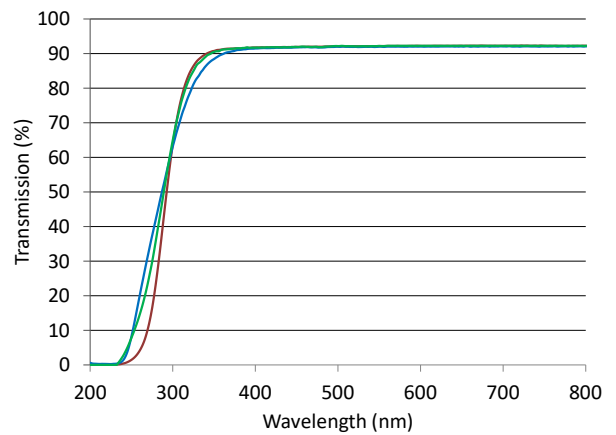
Property	SG 3.4	SG 7.8	SG 9.0
Density (g/cm ³)	2.38	2.39	2.42
Young's Modulus (GPa)	73.6	69.3	65.8
Fracture Toughness (MPa√m)	0.89	0.66	0.67
CTE (0-300°C, x10 ⁻⁶ /°C) as-drawn	3.4	7.8	8.7
Annealing Point (°C)	722	628	646
Refractive Index (589.3nm)	1.51	1.50	1.49

*Additional properties and CTE offerings available upon request

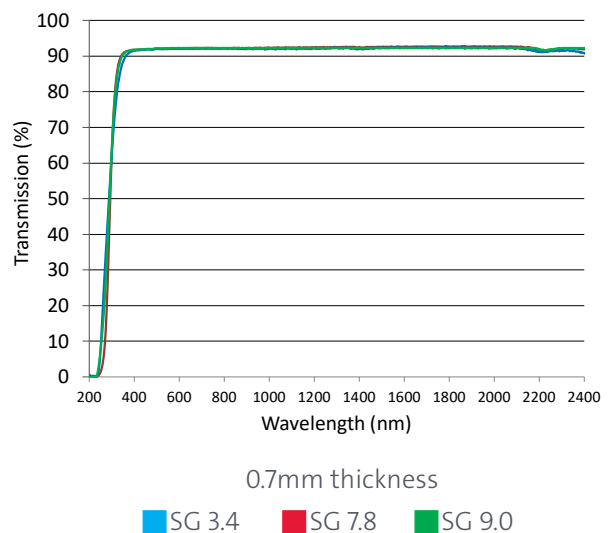
UV Transmission



Visible Transmission



IR Transmission



0.7mm thickness

■ SG 3.4 ■ SG 7.8 ■ SG 9.0

Precision Glass
Solutions

CORNING

Superior Standards

Carrier Solutions

Glass is highly transparent, has the ability to custom-match CTE, and has superior surface quality, thickness, and edge strength, making it an excellent material of choice for carrier substrates used in semiconductor manufacturing.

Corning Carrier Solutions offers precision glass carrier substrates in a wide range of CTEs with quick sampling to reduce customer development time. All samples are high-quality, optical-grade material with exceptionally low total thickness variation and a pristine surface.

Contact us
corning.com/precision-glass-solutions
precisionsg@corning.com

Regional Sales Offices

China

Corning China (Shanghai) Regional Headquarters
6F, Li Ming Building, 111 Gui Qing Road
Shanghai, 200233, China
t: 0086 21 3338 4338
f: 0086 21 3338 4300

Europe

Corning GmbH—Corning International
Abraham-Lincoln-Strasse 30
65189 Wiesbaden, Germany
t: +49 611 7366 159
f: +49 611 7366 143

Japan

Corning International K.K.
Akasaka Intercity 7th floor
1-11-44 Akasaka, Minato-ku
Tokyo, 107-0052, Japan
t: +81 3 3586 1052
f: +81 3 3587 0906

Korea

Corning Korea Company Ltd.
6th Fl., Gangnam Finance Center
152, Teheran-ro, Gangnam-gu,
Seoul, 06236, Korea
t: +82 2 796 9500
f: +82 2 796 9300

North America

Corning Incorporated
Corporate Headquarters
1 Riverfront Plaza
Corning, NY 14831
United States
t: 607 974 9000

Singapore

Corning Singapore Holdings Pet Ltd.
1, Kim Seng Promenade
Great World City
#9-11/12 West Tower
237994, Singapore
t: +65 65729740
f: +65 67352913

Taiwan

Corning Incorporated-Taiwan
8F, No. 8, Sec.3, Minsheng E. Rd.
Zhongshan Dist., Taipei City 10480
Taiwan
t: +886 2 2716 0338
f: +886 2 2516 7500